Newsletter 01/2021

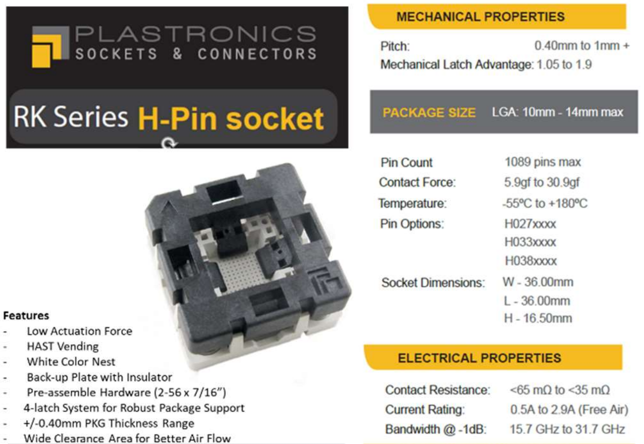
Goal of this newsletter is regular customer information. Do not hesitate to contact Quasys for more details about the topics inside of this newsletter. The newsletter contains a limited amount of information. We look forward to provide details about the solutions mentioned.

New Socket Series available from Plastronics

The new RK-Series

A new generation of H-Pin open Top socket with many features and an optimized design for small footprints and an excellent behaviour in your test environment.

Ask your responsible sales contact for more details.



PLASTRONICS SOCKETS & CONNECTORS

RK Series H-Pin socket

Features

- Low Actuation Force
- HAST Vending
- White Color Nest
- Back-up Plate with Insulator
- Pre-assemble Hardware (2-56 x 7/16")
- 4-latch System for Robust Package Support
- +/-0.40mm PKG Thickness Range
- Wide Clearance Area for Better Air Flow

MECHANICAL PROPERTIES

Pitch:	0.40mm to 1mm +
Mechanical Latch Advantage:	1.05 to 1.9

PACKAGE SIZE	LGA: 10mm - 14mm max
Pin Count	1089 pins max
Contact Force:	5.9gf to 30.9gf
Temperature:	-55ºC to +180ºC
Pin Options:	H027xxxx H033xxxx H038xxxx
Socket Dimensions:	W - 36.00mm L - 36.00mm H - 16.50mm

ELECTRICAL PROPERTIES

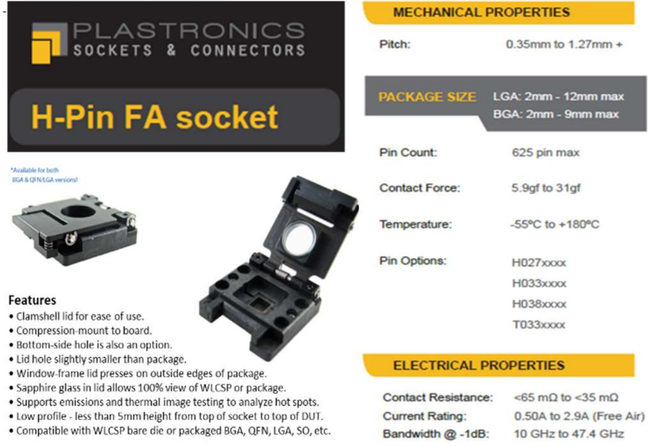
Contact Resistance:	<65 mΩ to <35 mΩ
Current Rating:	0.5A to 2.9A (Free Air)
Bandwidth @ -1dB:	15.7 GHz to 31.7 GHz

The new FA-Socket

A new generation of H-Pin socket for failure analysis. A clamshell socket which provides you access from top and/or bottom side.

Maximum openings for visual or physical access to your device combined with an excellent performance.

Ask your responsible sales contact for more details.



PLASTRONICS SOCKETS & CONNECTORS

H-Pin FA socket

*Available for both BGA & QFN/LGA versions!

Features

- Clamshell lid for ease of use.
- Compression-mount to board.
- Bottom-side hole is also an option.
- Lid hole slightly smaller than package.
- Window-frame lid presses on outside edges of package.
- Sapphire glass in lid allows 100% view of WLCSP or package.
- Supports emissions and thermal image testing to analyze hot spots.
- Low profile - less than 5mm height from top of socket to top of DUT.
- Compatible with WLCSP bare die or packaged BGA, QFN, LGA, SO, etc.

MECHANICAL PROPERTIES

Pitch:	0.35mm to 1.27mm +

PACKAGE SIZE	LGA: 2mm - 12mm max BGA: 2mm - 9mm max
Pin Count:	625 pin max
Contact Force:	5.9gf to 31gf
Temperature:	-55ºC to +180ºC
Pin Options:	H027xxxx H033xxxx H038xxxx T033xxxx

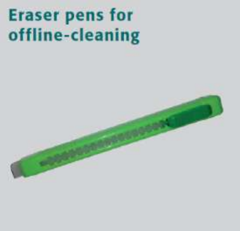
ELECTRICAL PROPERTIES

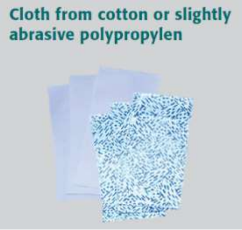
Contact Resistance:	<65 mΩ to <35 mΩ
Current Rating:	0.50A to 2.9A (Free Air)
Bandwidth @ -1dB:	10 GHz to 47.4 GHz

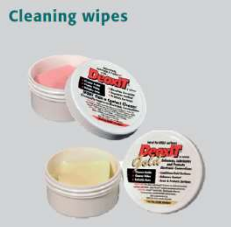
QUASYS has extended its product portfolio!

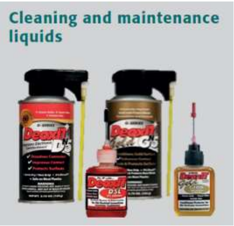
We offer cleaning products to keep your test equipment fit for production. Maintenance combined with an optimized cleaning recipe will improve your quality and lifetime. Benefit from proven quality products!

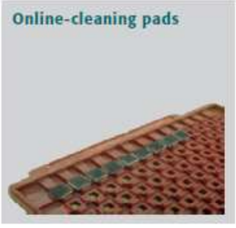
Ask for a specific consulting to your application and various cleaning methods.











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